DGG OR DGV PACKAGE

(TOP VIEW)

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- Member of the Texas Instruments Widebus™ Family
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I_{off} Supports Partial-Power-Down Mode Operation
- Sub 1-V Operable
- Max t_{pd} of 2 ns at 1.8 V
- Low Power Consumption, 10 μA at 1.8 V
- ◆ ±8-mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

This 18-bit universal bus transceiver is operational at 0.8-V to 2.7-V V_{CC} , but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

OEAB 56 GND 55 CLKAB LEAB 2 54 🛮 B1 A1 ∐3 GND ∏4 53 **∏** GND А2 Г 52 B2 5 A3 🛮 6 51 B3 50 V_{CC} V_{CC} []7 A4 🛮 8 49**∏** B4 A5 🛮 9 48 ∏ B5 A6 🛮 10 47 B6 GND [11 46 ☐ GND 45**∏** B7 A7 🛮 12 А8 П 44**∏** B8 13 43 B9 A9 [14 42 B10 A10 15 41 **∏** B11 A11 Π16 A12 l 17 40 ∏ B12 GND 118 39 GND A13 ∏ 19 38**∏** B13 A14 🛮 20 37**∏** B14 36 B15 A15 21 V_{CC} **□**22 35 V_{CC} A16 23 34 🛮 B16 A17 124 33 **∏** B17 GND [] 25 32 **∏** GND 31 T B18 A18 126 30 CLKBA OEBA 27

29 GND

LEBA

28

Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and OEBA is active low).

ORDERING INFORMATION

TA	PACKAG	eE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	TSSOP – DGG	Tape and reel	SN74AUC16501DGGR	AUC16501
–40°C to 85°C	TVSOP – DGV	Tape and reel	SN74AUC16501DGVR	MH501
	VFBGA – GQL	Tape and reel	SN74AUC16501GQLR	MH501

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor, and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

(TOP VIEW) 2 3 4 5 6 000000 000000 В 000000 С 000000 D \bigcirc \bigcirc Ε \bigcirc F \circ 000000 G 000000 Н 000000 J 000000 Κ

GQL PACKAGE

terminal assignments

	1	2	3	4	5	6
Α	A1	LEAB	OEAB	GND	CLKAB	B1
В	А3	A2	GND	GND	B2	В3
С	A5	A4	VCC	VCC	B4	B5
D	A7	A6	GND	GND	B6	В7
Ε	A9	A8			B8	B9
F	A10	A11			B11	B10
G	A12	A13	GND	GND	B13	B12
Н	A14	A15	Vcc	Vcc	B15	B14
J	A16	A17	GND	GND	B17	B16
K	A18	OEBA	LEBA	GND	CLKBA	B18

FUNCTION TABLE[†]

	INPUTS								
OEAB	LEAB	CLKAB	Α	В					
L	Х	Х	Х	Z					
Н	Н	Χ	L	L					
Н	Н	Χ	Н	Н					
Н	L	\uparrow	L	L					
Н	L	\uparrow	Н	Н					
Н	L	Н	Χ	в ₀ ‡ в ₀ §					
Н	L	L	Х	В ₀ §					

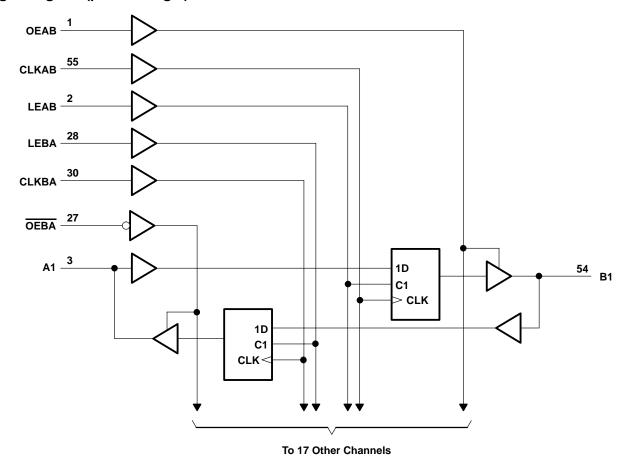
[†] A-to-B data flow is shown; B-to-A flow is similar, but uses OEBA, LEBA, and CLKBA.

[‡]Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low

[§] Output level before the indicated steady-state input conditions were established

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logic diagram (positive logic)



Pin numbers shown are for the DGG and DGV packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance or power-off state,	V_{O}
(see Note 1)	–0.5 V to 3.6 V
Output voltage range, V _O (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±20 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	64°C/W
DGV package	48°C/W
GQL package	42°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.



NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

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recommended operating conditions (see Note 3)

			MIN	MAX	UNIT	
Vcc	Supply voltage		0.8	2.7	V	
		V _{CC} = 0.8 V	Vcc			
V_{IH}	High-level input voltage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7			
		V _{CC} = 0.8 V		0		
V_{IL}	Low-level input voltage	$V_{CC} = 1.1 \text{ V to } 1.95 \text{ V}$		0.35 × V _{CC}	V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7		
٧ _I	Input voltage		0	3.6	V	
.,	Output well-are	Active state	0	Vcc		
۷O	Output voltage	3-state	0	3.6	V	
		V _{CC} = 0.8 V		-0.7		
		V _{CC} = 1.1 V		-3		
lOH	High-level output current	V _{CC} = 1.4 V		-5		
		V _{CC} = 1.65 V		-8		
		V _{CC} = 2.3 V		-9		
		V _{CC} = 0.8 V		0.7		
		V _{CC} = 1.1 V		3		
loL	Low-level output current	V _{CC} = 1.4 V		5	mA	
		V _{CC} = 1.65 V		8		
		V _{CC} = 2.3 V		9		
Δt/Δν	Input transition rise or fall rate	•		20	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN TYP1	MAX	UNIT
	I _{OH} = -100 μA	0.8 V to 2.7 V	V _{CC} -0.1		
	$I_{OH} = -0.7 \text{ mA}$	0.55			
Was a	$I_{OH} = -3 \text{ mA}$	1.1 V	0.8		V
VOH	$I_{OH} = -5 \text{ mA}$	1.4 V	1		V
	$I_{OH} = -8 \text{ mA}$	1.65 V	1.2		
	$I_{OH} = -9 \text{ mA}$	2.3 V	1.8		
	$I_{OL} = 100 \mu\text{A}$	0.8 V to 2.7 V		0.2	
	$I_{OL} = 0.7 \text{ mA}$	0.8 V	0.25		
	I _{OL} = 3 mA	1.1 V		0.3	V
VOL	I _{OL} = 5 mA	1.4 V		0.4	V
	I _{OL} = 8 mA	1.65 V		0.45	
	I _{OL} = 9 mA	2.3 V		0.6	
I _I Control inputs	$V_I = V_{CC}$ or GND	0.8 V to 2.7 V		±5	μΑ
l _{off}	V_I or $V_O = 2.7 V$	0		±10	μΑ
loz [‡]	$V_O = V_{CC}$ or GND	2.7 V		±10	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	0.8 V to 2.7 V		20	μΑ
Ci	$V_I = V_{CC}$ or GND	2.5 V	3.5	4.5	pF
C _{io}	$V_O = V_{CC}$ or GND	2.5 V	6	7.5	pF

 $[\]uparrow$ All typical values are at $T_A = 25^{\circ}$ C.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				V _{CC} = 0.8 V	V _{CC} =	1.2 V 1 V	V _{CC} =		V _{CC} =		V _{CC} =		UNIT
				TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock} Clock frequency		85		150		250		300		350	MHz		
	Pulse LE high			5.8	4		1.7		1.5		1.5		
t _W	duration	CLK high or low		5.8	4		1.7		1.5		1.5		ns
		Data before CLK1		0.2	0.6		0.6		0.6		0.6		
t _{su}	Setup time	Data batana LEI	CLK high	0.1	0.4		0.4		0.3		0.3		ns
	unio	Data before LE↓	CLK low	0.1	0.4		0.4		0.3		0.3		
	Hold	Data after CLK↑		0.3	1.2		1.1		0.9		0.9		
t _h	time	Data after LE↓	CLK high or low	1.3	1.5		1.3		1.2		1.2		ns

[‡] For I/O ports, the parameter IOZ includes the input leakage current.

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER FROM		то	V _{CC} = 0.8 V	= 0.8 V $\begin{vmatrix} V_{CC} = 1.2 \text{ V} \\ \pm 0.1 \text{ V} \end{vmatrix}$ $\begin{vmatrix} V_{CC} = 1.5 \text{ V} \\ \pm 0.1 \text{ V} \end{vmatrix}$		V _{CC} = 1.8 V ± 0.15 V			V _{CC} = 2.5 V ± 0.2 V		UNIT		
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
f _{max}			85		150		250			300		350	MHz
^t pd	A or B	B or A	8.5	0.9	4	1	2.8	0.3	2	2.8	0.1	2.3	ns
^t pd	LE	A or B	9.8	1.6	6.3	1	4.1	0.9	2.5	3.8	0.7	3	ns
^t pd	CLK	AUID	9.2	1.5	3.8	0.7	3.1	0.9	2.2	3.3	0.6	2.7	ns
t _{en}	OEAB	В	9.7	1.6	3	1.1	3.2	1	1.8	3.4	0.8	2.8	ns
^t dis	OEAB	Б	15	3.6	5.3	0.9	5.7	1.7	2.4	3.2	1	3.1	ns
t _{en}	OEBA	Δ.	11	1.7	5.7	1	3.7	1	2.2	3.7	0.7	3	ns
^t dis	OEBA	Α	18	3.5	7.5	1.4	5.4	2	3.5	5.2	0.9	3	ns

operating characteristics for transparent mode, T_A = 25°C

	PARAMETER		TEST	V _{CC} = 0.8 V	V _{CC} = 1.2 V	V _{CC} = 1.5 V	V _{CC} = 1.8 V	V _{CC} = 2.5 V	LINUT
	FARAINETER		CONDITIONS	TYP	TYP	TYP	TYP	TYP	UNIT
C _{pd†} (each bit)	Power dissipation capacitance	Outputs enabled, 1 output switching	$\begin{aligned} &1 \: f_{\text{data}} = 10 \: \text{MHz}, \\ &f_{\text{clk}} = V_{\text{CC}} \: \text{or} \\ &\text{GND}, \\ &1 \: f_{\text{out}} = 10 \: \text{MHz}, \\ &\underbrace{OEAB}_{} = V_{\text{CC}}, \\ &\underbrace{OEBA}_{} = GND, \\ &\text{LE} = V_{\text{CC}}, \\ &\text{C}_{\text{L}} = 0 \: \text{pF} \end{aligned}$	30	31	33	36	44	pF
C _{pd} (each bit)	Power dissipation capacitance	Outputs disabled	$\begin{aligned} &1 \: f_{data} = 10 \: \text{MHz}, \\ &f_{Clk} = V_{CC} \: \text{or} \\ &\text{GND}, \\ &1 \: f_{out} = \text{not} \\ &\text{switching}, \\ &\underbrace{OEAB}_{} = \text{GND}, \\ &\underbrace{OEBA}_{} = V_{CC}, \\ &\text{LE} = V_{CC}, \\ &\text{CL} = 0 \: \text{pF} \end{aligned}$	9	9	10	12	16	pF

[†]C_{pd} (each output) is the C_{pd} for each data bit (input and output circuitry) as it operates at 5 MHz (the clock is operating at 10 MHz in this test, but its I_{CC} component has been subtracted out).



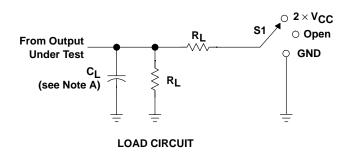
operating characteristics for clocked mode, $T_A = 25^{\circ}C^{\dagger}$

	PARAMETER	1	TEST CONDITIONS	V _{CC} = 0.8 V TYP	V _{CC} = 1.2 V TYP	V _{CC} = 1.5 V TYP	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	UNIT
C _{pd} ‡ (each bit)	Power dissipation capacitance	Outputs enabled, 1 output switching	$\begin{array}{l} 1 \text{ f}_{data} = 5 \text{ MHz}, \\ 1 \text{ f}_{clk} = 10 \text{ MHz}, \\ 1 \text{ f}_{out} = 5 \text{ MHz}, \\ \underline{OEAB} = V_{CC}, \\ \overline{OEBA} = GND, \\ LE = GND, \\ C_L = 0 \text{ pF} \end{array}$	29	30	31	35	43	pF
C _{pd} (Z)	Power dissipation capacitance	Outputs disabled, 1 clock and 1 data switching	$\begin{array}{l} 1 \: f_{data} = 5 \: \text{MHz}, \\ 1 \: f_{Clk} = 10 \: \text{MHz}, \\ f_{out} = \text{not} \\ \text{switching}, \\ \underline{OEAB} = \text{GND}, \\ \overline{OEBA} = V_{CC}, \\ \text{LE} = \text{GND}, \\ C_L = 0 \: \text{pF} \end{array}$	8	8	9	10	13	pF
C _{pd} § (each clock)	Power dissipation capacitance	Outputs disabled, clock only switching	$\begin{array}{l} 1 f_{data} = 0 \text{ MHz}, \\ 1 f_{Clk} = 10 \text{ MHz}, \\ f_{out} = \text{not} \\ \text{switching}, \\ \underline{OEAB} = \text{GND}, \\ \underline{OEBA} = \text{V}_{CC}, \\ \text{LE} = \text{GND}, \\ \text{C}_{L} = 0 \text{ pF} \end{array}$	31	32	32	34	39	pF

[†] Total device C_{pd} for multiple (n) outputs switching and (y) clocks inputs switching = {n * C_{pd} (each output)} + {y * C_{pd} (each clock)} ‡ C_{pd} (each bit) is the C_{pd} for each data bit (input and output circuitry) as it operates at 5 MHz (the clock is operating at 10 MHz in this test, but its I_{CC} component has been subtracted out). § C_{pd} (each clock) is the C_{pd} for the clock circuitry only as it operates at 10 MHz.

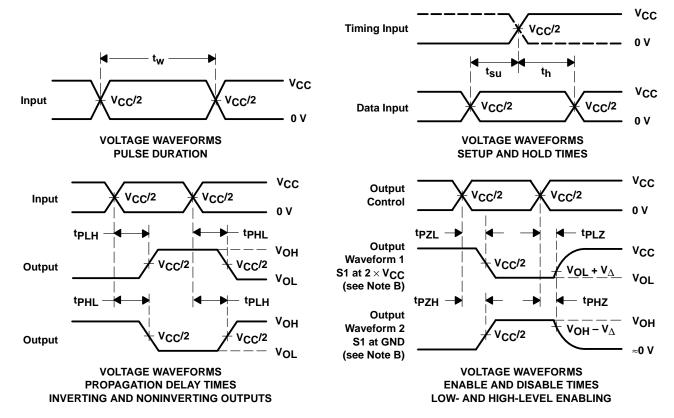
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PARAMETER MEASUREMENT INFORMATION



TEST	S 1
tPLH/tPHL	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	GND

V _{CC}	CL	RL	${f v}_{\Delta}$
0.8 V	15 pF	2 k Ω	0.1 V
1.2 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.5 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.8 V \pm 0.15 V	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	30 pF	500 Ω	0.15 V



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, slew rate \geq 1 V/ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpZL and tpZH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

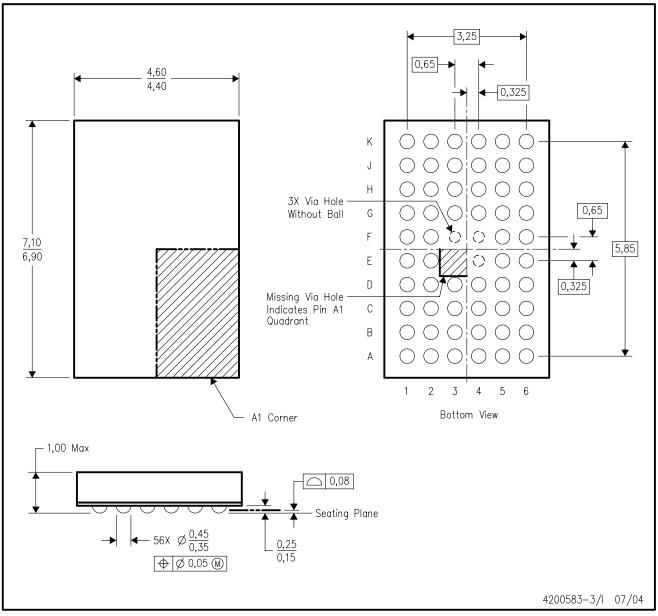
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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